PCN Number:	20180501001.1	PCN Date:	May 3 2018
Title:	Qualification of additional Fab site (DMOS6) and Assembly/Bump site (JCAP) option for the TAS2557YZR/T		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	Aug 3 2018	Estimated Sample Availability:	Date provided at sample request.

Change Type:

☒	Assembly Site	☐	Assembly Process	☐	Assembly Materials
☐	Design	☐	Electrical Specification	☐	Mechanical Specification
☒	Test Site	☐	Packing/Shipping/Labeling	☐	Test Process
☒	Wafer Bump Site	☐	Wafer Bump Material	☐	Wafer Bump Process
☒	Wafer Fab Site	☐	Wafer Fab Materials	☐	Wafer Fab Process
		☐	Part number change		

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly/bump (JCAP) site for the TAS2557YZR/T.

Current Fab Site				Additional Fab Site			
Fab Site	Process	Bump Site	Wafer Diameter	Fab Site	Process	Bump Site	Wafer Diameter
RFAB	LBC8	Clark-BP	300 mm	DMOS6	LBC8	JCAP-BP	300 mm

There are no material difference between devices currently manufactured and devices built with this manufacturing option.

Reason for Change:

Continuity of Supply

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website.

Changes to product identification resulting from this PCN:

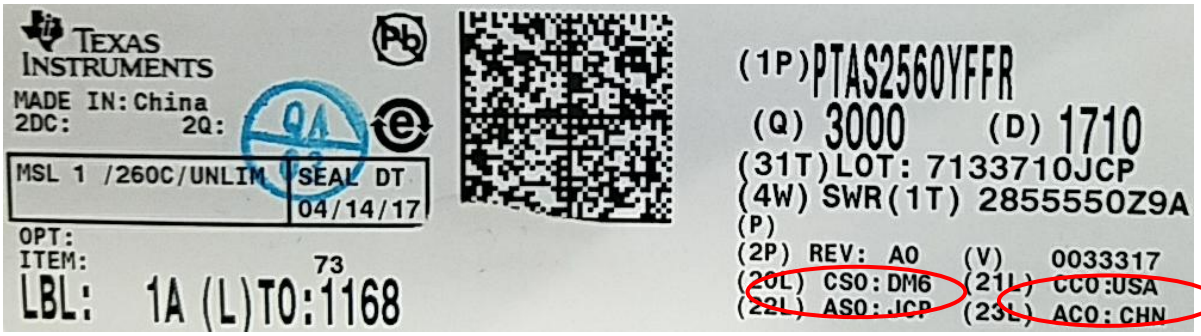
Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
DMOS6	**DM6**	**USA**	**Dallas**

Assembly Site Information:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (21L)	Assembly City
Clark	QAB	THA	Bangkok
JCAP	**JCP**	**CHN**	**Jiangyin**

Sample product shipping label (not actual product label)



Product Affected:

TAS2557YZR	TAS2557YZT

TI Information
Selective Disclosure

Qualification Report

TAS2557/9 in (DMOS6/JCAP)
Approve Date 19-Apr-2018

Product Attributes

Attributes	Qual Device: TAS2557YZ	QBS Package Reference: CD3230A0YFF
Assembly Site	JCAP	JCAP
Package Family	DSBGA	DSBGA
Flammability Rating	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	DM6	RFAB
Wafer Process	LBC8LV	LBC7

- QBS: Qual By Similarity
- Qual Device TAS2557YZ is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TAS2557YZ	QBS Package Reference: CD3230A0YFF
ED	Electrical Characterization	Per Datasheet Parameters	-	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0
HBM	ESD - HBM	2500 V	-	-
CDM	ESD - CDM	1500 V	-	-
HTOL	Life Test, 125C	1000 Hours	-	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0
SBS	Bump-Shear	--	1/36/0	3/150/0
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

TI Information
Selective Disclosure

Qualification Report

TAS2557/9 in (RFAB/JCAP)
Approve Date 05-Apr-2018

Product Attributes

Attributes	Qual Device: TAS2557YZ	QBS Package Reference: CD3230A0YFF	QBS Package Reference: LM3566A0YFFR
Assembly Site	JCAP	JCAP	CLARK
Package Family	DSBGA	DSBGA	DSBGA
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB	RFAB	RFAB
Wafer Process	LBC8LV	LBC7	LBC8LV

- QBS: Qual By Similarity
- Qual Device TAS2557YZ is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TAS2557YZ	QBS Package Reference: CD3230A0YFF	QBS Package Reference: LM3566A0YFFR
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0	1/77/0
HBM	ESD - HBM	2500 V	-	-	1/3/0
CDM	ESD - CDM	1500 V	-	-	1/3/0
HTOL	Life Test, 125C	1000 Hours	-	1/77/0	1/77/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/231/0	1/77/0
LU	Latch-up	(per JESD78)	-	-	1/6/0
PD	Physical Dimensions	--	-	3/15/0	-
SBS	Bump-Shear	Bumps	1/36/0	3/150/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	1/77/0	3/231/0	-
TC	Temperature Cycle, -65/150C	500 Cycles	-	-	1/77/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	1/77/0	3/231/0	1/77/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

Qualification Report

TAS2557YZ (RFAB/DMOS6 MFF)
Approve Date 19-Apr-2018

Product Attributes

Attributes	Qual Device: TAS2557YZ	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF
Assembly Site	CLARK-AT	CLARK-AT	CLARK-AT
Package Family	DSBGA	DSBGA	DSBGA
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	RFAB/DMOS6 (MFF)	RFAB/DMOS6 (MFF)	RFAB/DMOS6 (MFF)
Wafer Process	LBC8LV	LBC8LV	LBC8LV

- QBS: Qual By Similarity
- Qual Device TAS2557YZ is qualified at LEVEL1-260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: TAS2557YZ	QBS Process Reference: TAS2552YFF	QBS Process Reference: TAS2553YFF
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	-	Pass
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	3/3000/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HBM	ESD - HBM	4000 V	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	3/9/0
HTOL	Life Test, 125C	1000 Hours	-	-	3/231/0
HTSL	High Temp. Storage Bake, 170C	420 Hours	-	3/228/0	-
LU	Latch-up	(per JESD78)	1/6/0	-	3/18/0
SBS	Bump Shear	Solder Bumps	1/36/0	3/108/0	-
TC	Temperature Cycle, -55/125C	700 Cycles	-	3/231/0	-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	3/228/0	-

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

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Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below, or you can contact your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com